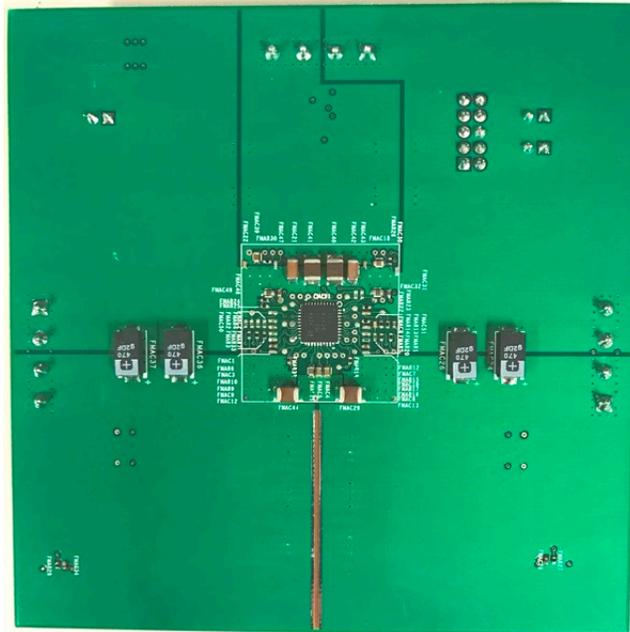
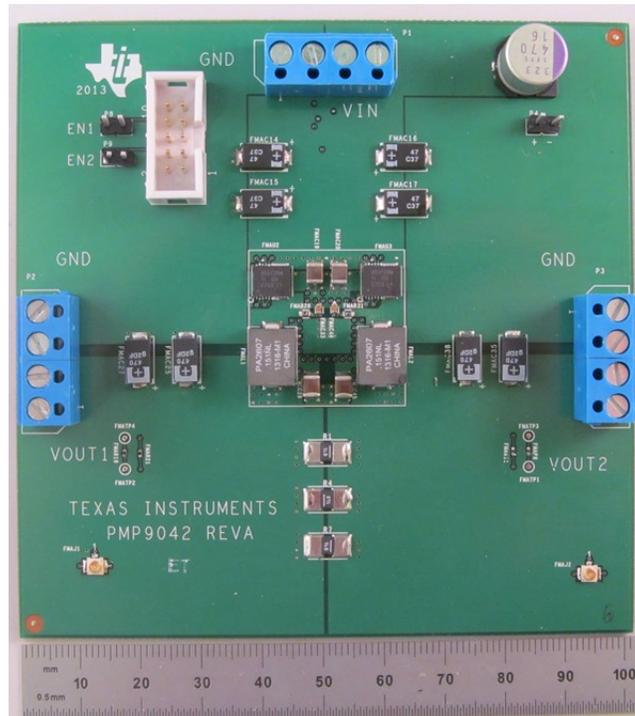
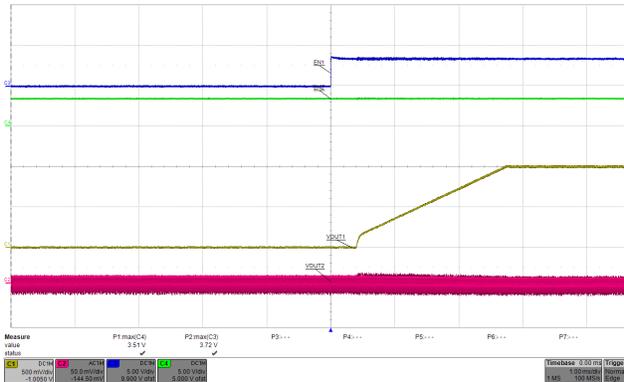


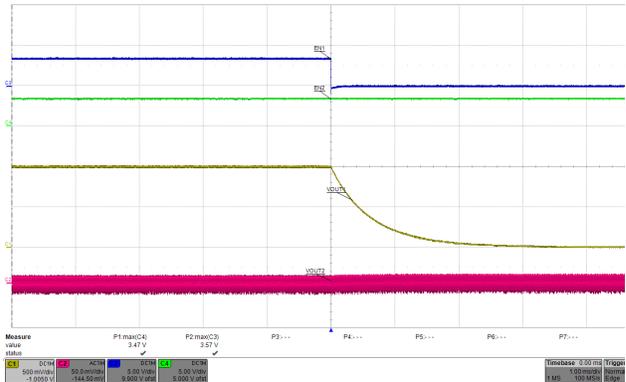
Photo of the prototype



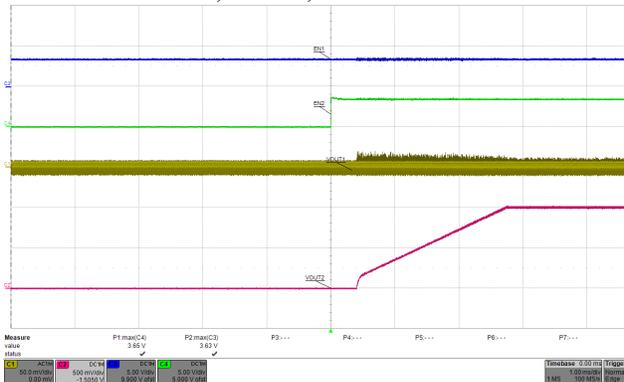
1 Startup and shutdown



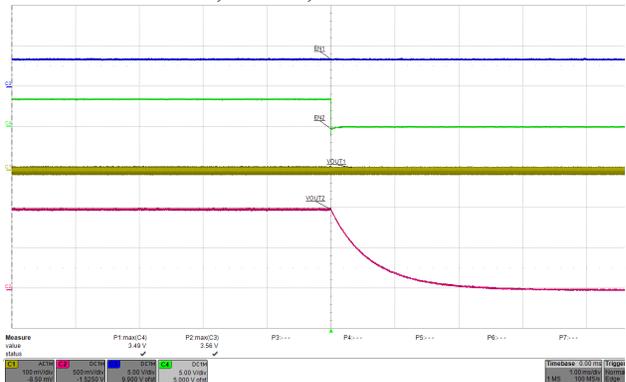
12Vin, Ch2 on, Ch1 off to on



12Vin, Ch2 on, Ch1 on to off



12Vin, Ch1 on, Ch2 off to on



12Vin, Ch1 on, Ch2 on to off

2 Output Ripple

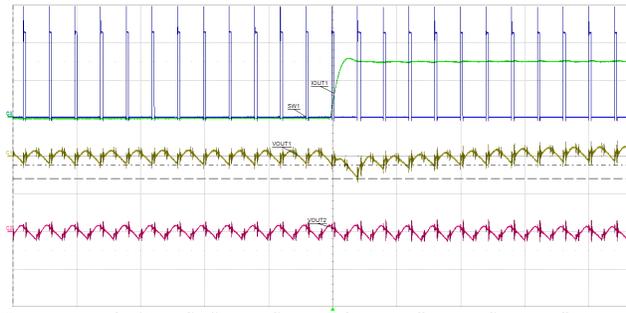


12Vin, Ch1 at 10% load, Ch2 at 100% load (2x 100uF, 6.3V, 1210+4x470uF, 4V, 7343)

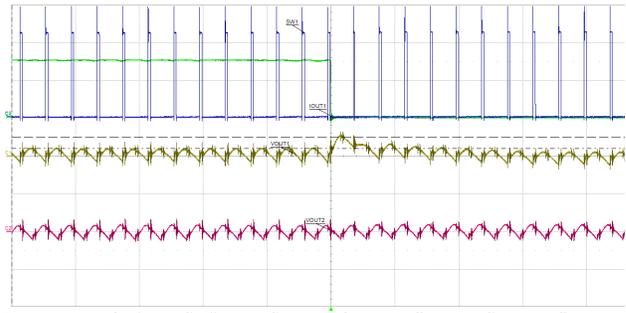


12Vin, Ch1 at 100% load, Ch2 at 10% load (2x 100uF, 6.3V, 1210+4x470uF, 4V, 7343)

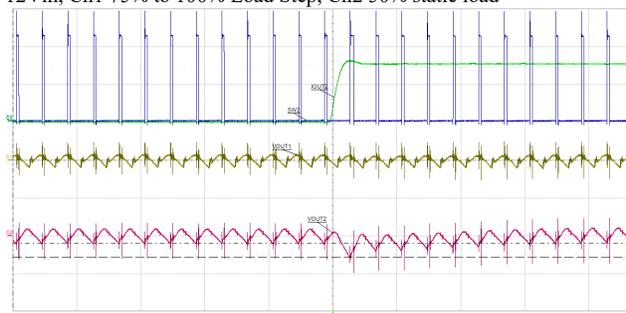
3 Transient



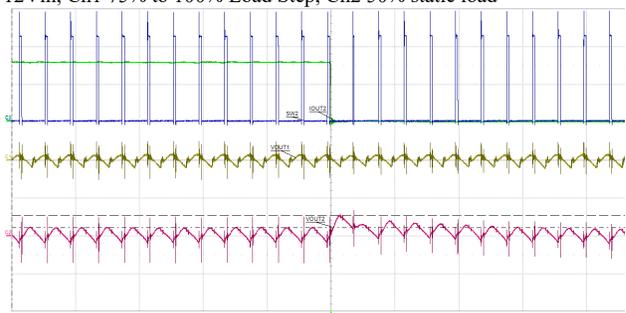
12Vin, Ch1 75% to 100% Load Step, Ch2 50% static load



12Vin, Ch2 75% to 100% Load Step, Ch1 50% static load

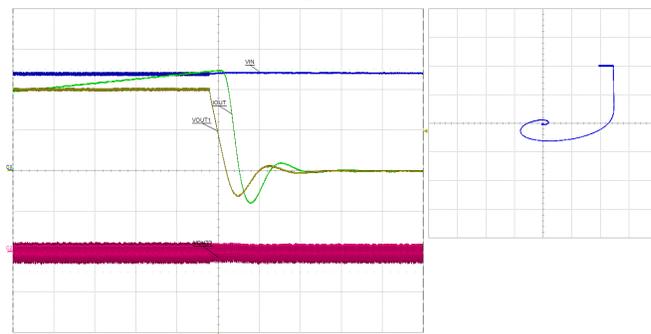


12Vin, Ch2 75% to 100% Load Step, Ch1 50% static load

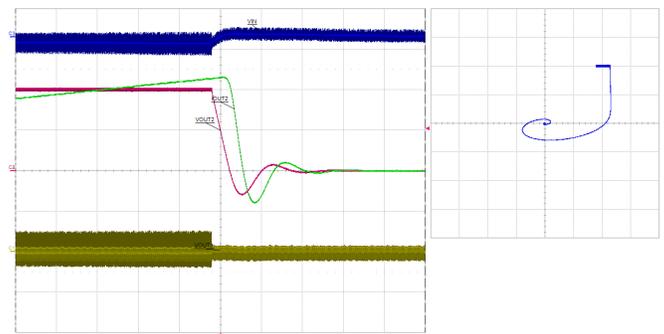


12Vin, Ch2 75% to 100% Load Step, Ch1 50% static load

4 Over-Current protection

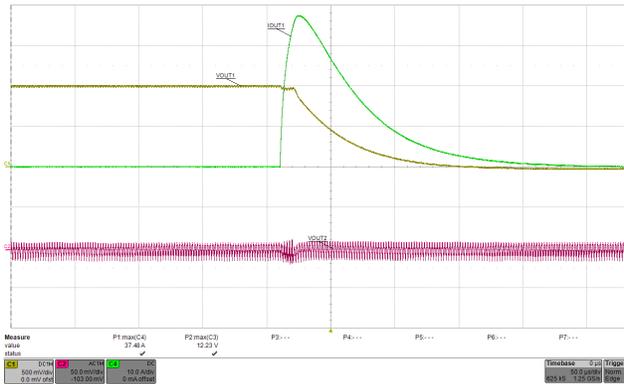


12Vin, Ch1 load regulation and over-current protection, Ch2 10% load

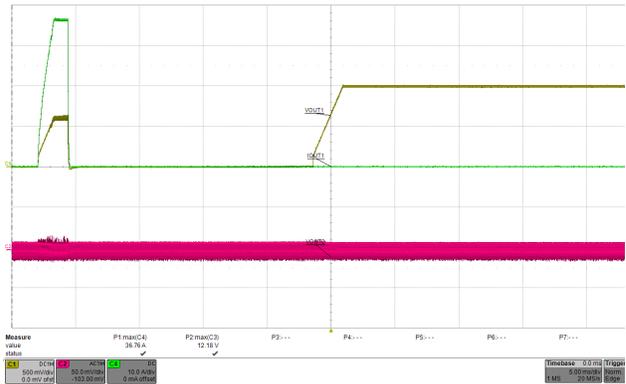


12Vin, Ch2 load regulation and over-current protection, Ch1 10% load

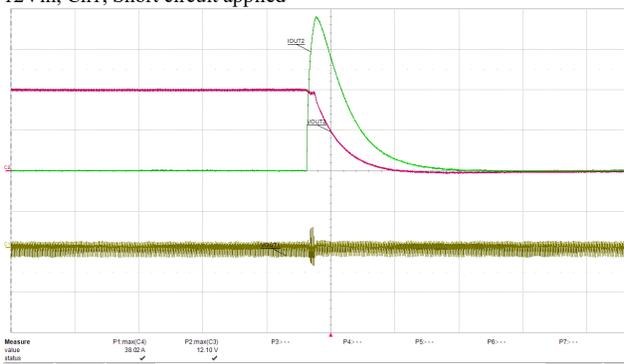
5 Short-Circuit Protection



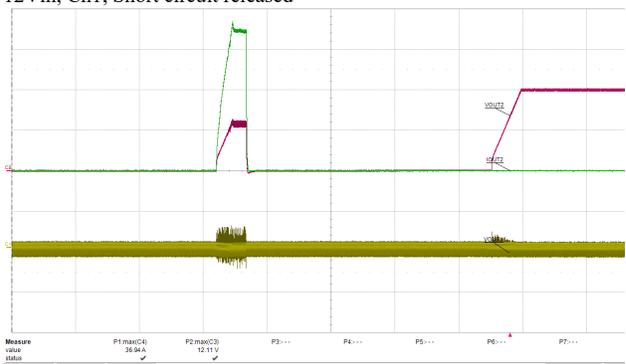
12Vin, Ch1, Short circuit applied



12Vin, Ch1, Short circuit released

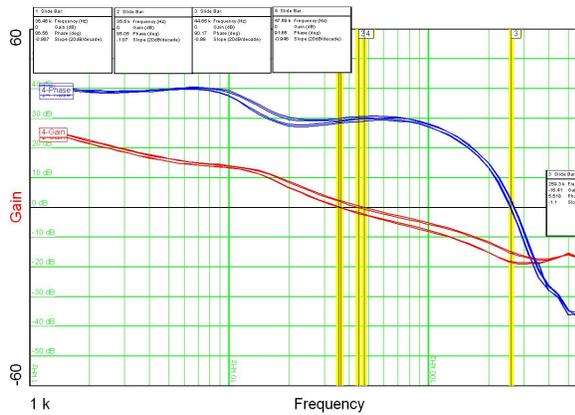


12Vin, Ch2, Short circuit applied

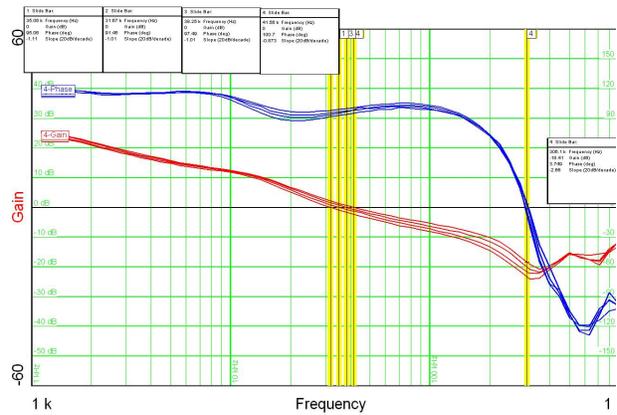


12Vin, Ch2, Short circuit released

6 Bode Plot

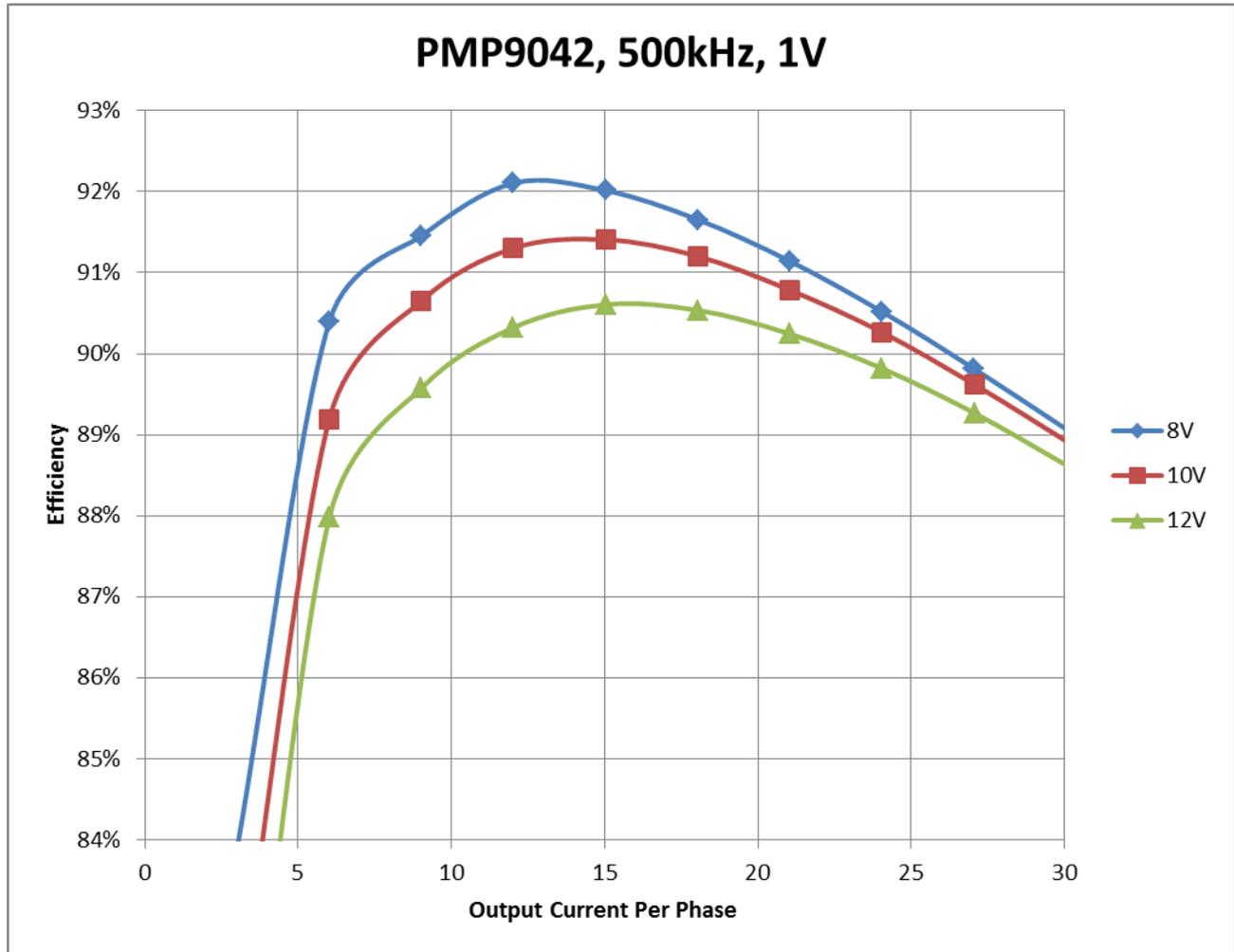


CH1, 1V, 30A, VIN=7V, 8V, 10V, 12V(BW=48kHz, PM=92D)

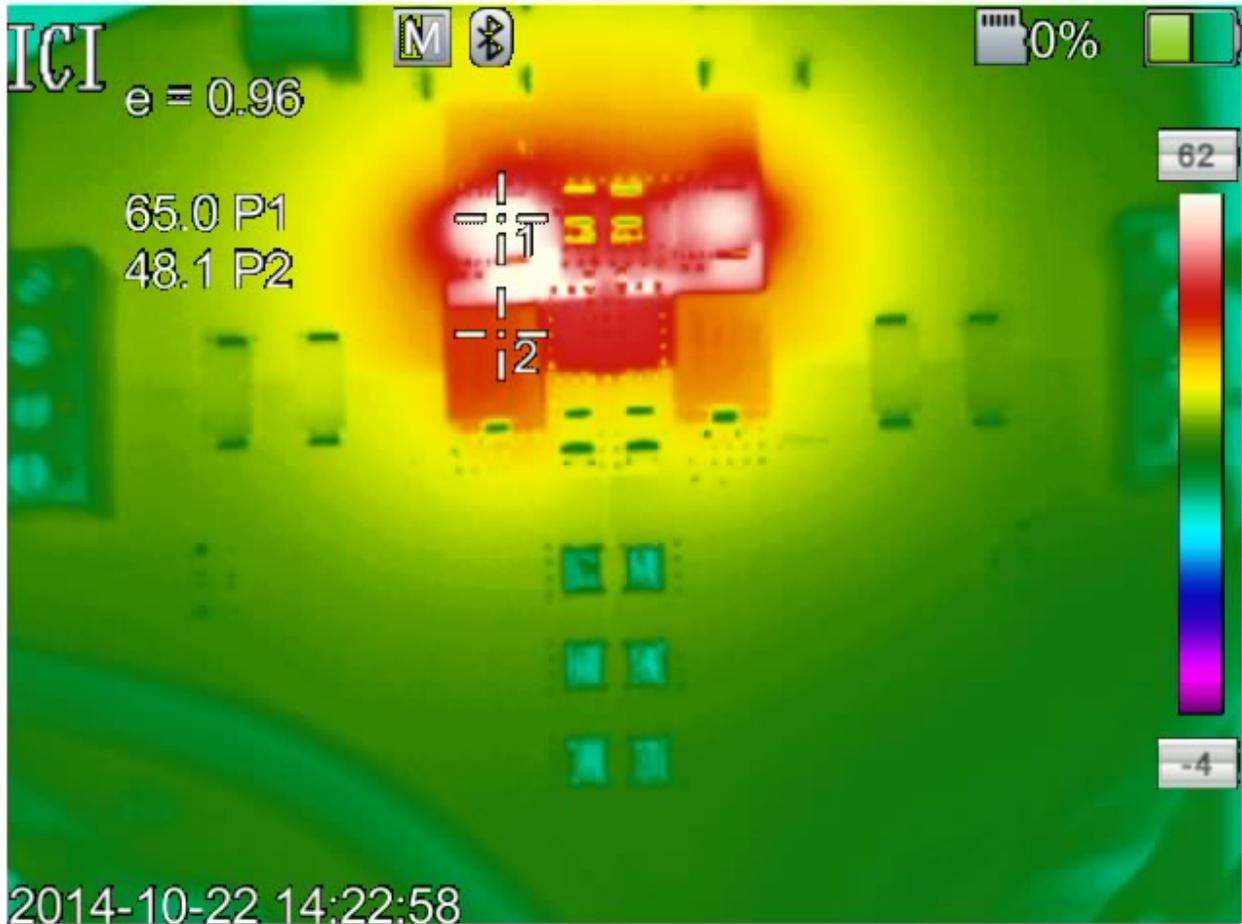


CH2, 1V, 30A, VIN=7V, 8V, 10V, 12V(BW=41.6kHz, PM=101D)

7 Efficiency



8 Thermal



Test conditions: 12Vin, Vout1=1V/30A, Vout2=1V/30A, 300kHz, 200LFM Forced Convection, 25C ambient temperature. ($T_{FET}=65C$, $T_{IND}=48.1C$)

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